- Optimized for Off-Line and dc-to-dc Converters
- Low Start-Up Current (<1 mA)
- Automatic Feed-Forward Compensation
- Pulse-by-Pulse Current Limiting
- Enhanced Load-Response Characteristics
- Undervoltage Lockout With Hysteresis
- Double-Pulse Suppression
- High-Current Totem-Pole Output
- Internally Trimmed Bandgap Reference
- 500-kHz Operation
- Error Amplifier With Low Output Resistance
- Designed to Be Interchangeable With UC2842 and UC3842 Series

D PACKAGE (TOP VIEW) сомрГ Π REF 14 □ NC NC 2 13 VFB∏3 12 | V_{CC} NC 4 11 U VC ISENSE [] 5 10 NC 6 9 **[**] GND RT/CT[8 POWER GROUND

NC - No internal connection

COMP 1 8 REF VFB 2 7 VCC ISENSE 3 6 OUTPUT RT/CT 4 5 GND

description/ordering information

The TL284x and TL384x series of control integrated circuits provide the features that are

necessary to implement off-line or dc-to-dc fixed-frequency current-mode control schemes, with a minimum number of external components. Some of the internally implemented circuits are an undervoltage lockout (UVLO), featuring a start-up current of less than 1 mA, and a precision reference trimmed for accuracy at the error amplifier input. Other internal circuits include logic to ensure latched operation, a pulse-width modulation (PWM) comparator (that also provides current-limit control), and a totem-pole output stage designed to source or sink high-peak current. The output stage, suitable for driving N-channel MOSFETs, is low when it is in the off state.

Major differences between members of these series are the UVLO thresholds and maximum duty-cycle ranges. Typical UVLO thresholds of 16 V (on) and 10 V (off) on the TLx842 and TLx844 devices make them ideally suited to off-line applications. The corresponding typical thresholds for the TLx843 and TLx845 devices are 8.4 V (on) and 7.6 V (off). The TLx842 and TLx843 devices can operate to duty cycles approaching 100%. A duty-cycle range of 0 to 50% is obtained by the TLx844 and TLx845 by the addition of an internal toggle flip-flop, which blanks the output off every other clock cycle.

The TL284x-series devices are characterized for operation from -40° C to 85° C. The TL384x-series devices are characterized for operation from 0° C to 70° C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



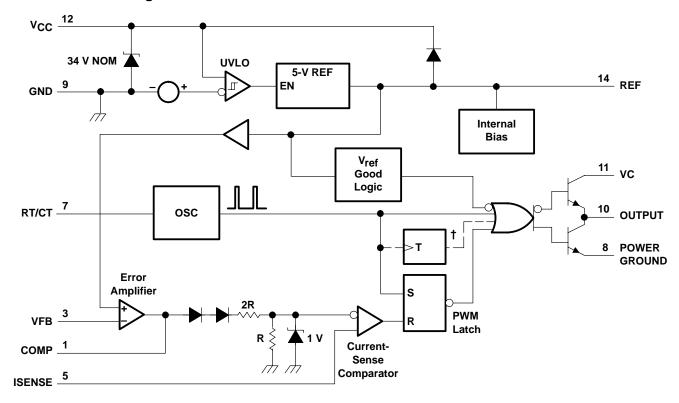
ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
			TL3842P	TL3842P
	PDIP (P)	Tub = +1 50	TL3843P	TL3843P
	(8 pin)	Tube of 50	TL3844P	TL3844P
			TL3845P	TL3845P
		Tube of 75	TL3842D-8	TI 2040
		Reel of 2500	TL3842DR-8	TL3842
		Tube of 75 TL3843D-8		TI 2040
	SOIC (D)	Reel of 2500	TL3843DR-8	TL3843
	(8 pin) ´	Tube of 75	TL3844D-8	TI 0044
000 1- 7000		Reel of 2500	TL3844DR-8	TL3844
0°C to 70°C		Tube of 75	TL3845D-8	TI 0045
		Reel of 2500	TL3845DR-8	TL3845
		Tube of 50	TL3842D	TI 0040
		Reel of 2500	TL3842DR	TL3842
		Tube of 50	TL3843D	TI 00.40
	SOIC (D)	Reel of 2500	TL3843DR	TL3843
	(14 pin)	Tube of 50	TL3844D	TI 0044
		Reel of 2500	TL3844DR	TL3844
		Tube of 50	TL3845D	TI 00.45
		Reel of 2500	TL3845DR	TL3845
			TL2842P	TL2842P
	PDIP (P)		TL2843P	TL2843P
	(8 pin) ´	Tube of 50	TL2844P	TL2844P
			TL2845P	TL2845P
		Tube of 75	TL2842D-8	TI 00.40
		Reel of 2500	TL2842DR-8	TL2842
		Tube of 75	TL2843D-8	TI 00.40
	SOIC (D)	Reel of 2500	TL2843DR-8	TL2843
	(8 pin) ´	Tube of 75	TL2844D-8	TI 00.44
4000 / 0500		Reel of 2500	TL2844DR-8	TL2844
–40°C to 85°C		Tube of 75	TL2845D-8	TI 00.45
		Reel of 2500	TL2845DR-8	TL2845
		Tube of 50	TL2842D	TI 00.40
		Reel of 2500	TL2842DR	TL2842
		Tube of 50	TL2843D	TI 0040
	SOIC (D)	Reel of 2500	TL2843DR	TL2843
	(14 pin)	Tube of 50	TL2844D	TI 00.44
		Reel of 2500	TL2844DR	TL2844
		Tube of 50	TL2845D	TI 00.45
		Reel of 2500	TL2845DR	TL2845

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



functional block diagram



 $\mbox{$^{\dag}$}$ The toggle flip-flop is present only in TL2844, TL2845, TL3844, and TL3845. Pin numbers shown are for the D (14-pin) package.



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage (see Note 1) (I _{CC} < 30 mA)		Self limiting
Analog input voltage range, V _I (VFB and ISENSE)		-0.3 V to 6.3 V
Output voltage, VO (OUTPUT)		35 V
Input voltage, V _I , (VC, D package only)		35 V
Supply current, I _{CC}		
Output current, I _O		±1 A
Error amplifier output sink current		
Package thermal impedance, θ_{JA} (see Notes 2 and 3):	D package	86°C/W
	D-8 package	97°C/W
	P package	85°C/W
Virtual junction temperature, T _J		150°C
Output energy (capacitive load)		5 μJ
Lead temperature, 1,6 mm (1/16 inch) from case for 10	seconds	260°C
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages are with respect to the device GND terminal.
 - 2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can impact reliability.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

			MIN	NOM	MAX	UNIT
V _{CC} and VC [‡]	Supply voltage				30	V
V _I , RT/CT	Input voltage		0		5.5	V
V _I , VFB and ISENSE	Input voltage		0		5.5	V
V _O , OUTPUT	Output voltage		0		30	V
VO, POWER GROUND‡	Output voltage		-0.1		1	V
Icc	Supply current, externally limited				25	mA
IO	Average output current				200	mA
I _{O(ref)}	Reference output current				-20	mA
fosc	Oscillator frequency			100	500	kHz
_		TL284x	-40		85	
TA	Operating free-air temperature	TL384x	0		70	°C

[‡]These recommended voltages for VC and POWER GROUND apply only to the D package.



electrical characteristics over recommended operating free-air temperature range, V_{CC} = 15 V (see Note 4), R_T = 10 k Ω , C_T = 3.3 nF (unless otherwise specified)

reference section

DADAMETER	TEST OF	NDITIONS		TL284x				UNIT	
PARAMETER	TEST CONDITIONS		MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNII
Output voltage	$I_O = 1 \text{ mA},$	T _A = 25°C	4.95	5	5.05	4.9	5	5.1	V
Line regulation	V _{CC} = 12 V to 25 V			6	20		6	20	mV
Load regulation	$I_O = 1 \text{ mA to } 20 \text{ mA}$			6	25		6	25	mV
Temperature coefficient of output voltage				0.2	0.4		0.2	0.4	mV/°C
Output voltage with worst-case variation	V _{CC} = 12 V to 25 V,	I _O = 1 mA to 20 mA	4.9		5.1	4.82		5.18	V
Output noise voltage	f = 10 Hz to 10 kHz,	T _A = 25°C		50			50		μV
Output-voltage long-term drift	After 1000 h at T _A = 2	25°C		5	25		5	25	mV
Short-circuit output current			-30	-100	-180	-30	-100	-180	mA

[†] All typical values are at $T_A = 25$ °C.

NOTE 4: Adjust VCC above the start threshold before setting it to 15 V.

oscillator section

PARAMETER	TEST CONDITIONS	TL284x			TL384x			UNIT
PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
Oscillator frequency (see Note 5)	T _A = 25°C	47	52	57	47	52	57	kHz
Frequency change with supply voltage	V _{CC} = 12 V to 25 V		2	10		2	10	Hz/kHz
Frequency change with temperature			50			50		Hz/kHz
Peak-to-peak amplitude at RT/CT			1.7			1.7		V

[†] All typical values are at T_A = 25°C.

NOTES: 4. Adjust V_{CC} above the start threshold before setting it to 15 V.

5. Output frequency equals oscillator frequency for the TLx842 and TLx843. Output frequency is one-half the oscillator frequency for the TLx844 and TLx845.

error-amplifier section

DADAMETED	7507	TEST CONDITIONS					UNIT		
PARAMETER	TEST CONDITIONS		MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNII
Feedback input voltage	COMP at 2.5 V		2.45	2.50	2.55	2.42	2.50	2.58	V
Input bias current				-0.3	-1		-0.3	-2	μΑ
Open-loop voltage amplification	V _O = 2 V to 4 V		65	90		65	90		dB
Gain-bandwidth product			0.7	1		0.7	1		MHz
Supply-voltage rejection ratio	V _{CC} = 12 V to 2	25 V	60	70		60	70		dB
Output sink current	VFB at 2.7 V,	COMP at 1.1 V	2	6		2	6		mA
Output source current	VFB at 2.3 V,	COMP at 5 V	-0.5	-0.8		-0.5	-0.8		mA
High-level output voltage	VFB at 2.3 V,	$R_L = 15 \text{ k}\Omega \text{ to GND}$	5	6		5	6		V
Low-level output voltage	VFB at 2.7 V,	$R_L = 15 \text{ k}\Omega \text{ to GND}$		0.7	1.1		0.7	1.1	V

[†] All typical values are at $T_A = 25$ °C.

NOTE 4: Adjust V_{CC} above the start threshold before setting it to 15 V.



electrical characteristics over recommended operating free-air temperature range, $V_{CC} = 15 \text{ V}$ (see Note 4), $R_T = 10 \text{ k}\Omega$, $C_T = 3.3 \text{ nF}$ (unless otherwise specified) (continued)

current-sense section

PARAMETER	TEST CONDITIONS -		TL284x				UNIT		
PARAMETER			MIN	TYP†	MAX	MIN	TYP [†]	MAX	UNII
Voltage amplification	See Notes 6 and 7		2.85	3	3.13	2.85	3	3.15	V/V
Current-sense comparator threshold	COMP at 5 V,	See Note 6	0.9	1	1.1	0.9	1	1.1	V
Supply-voltage rejection ratio	$V_{CC} = 12 \text{ V to } 25 \text{ V},$	See Note 6		70			70		dB
Input bias current				-2	-10		-2	-10	μΑ
Delay time to output				150	300		150	300	ns

[†] All typical values are at $T_A = 25$ °C.

NOTES: 4. Adjust V_{CC} above the start threshold before setting it to 15 V.

- 6. These parameters are measured at the trip point of the latch, with VFB at 0 V.
- 7. Voltage amplification is measured between ISENSE and COMP, with the input changing from 0 V to 0.8 V.

output section

PARAMETER	TEST CONDITIONS	TL284x				UNIT		
PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	MIN	TYP [†]	MAX	UNIT
High-level output voltage	I _{OH} = -20 mA	13	13.5		13	13.5		V
r light-level output voltage	I _{OH} = -200 mA	12	13.5		12	13.5		V
Low-level output voltage	I _{OL} = 20 mA		0.1	0.4		0.1	0.4	V
Low-level output voltage	I _{OL} = 200 mA		1.5	2.2		1.5	2.2	V
Rise time	$C_L = 1 \text{ nF}, \qquad T_A = 25^{\circ}C$		50	150		50	150	ns
Fall time	$C_L = 1 \text{ nF}, \qquad T_A = 25^{\circ}C$		50	150		50	150	ns

[†] All typical values are at $T_A = 25$ °C.

NOTE 4: Adjust V_{CC} above the start threshold before setting it to 15 V.

undervoltage-lockout section

PARAMETER			TL284x			TL384x		
			TYP†	MAX	MIN	TYP [†]	MAX	UNIT
Start threshold voltage	TLx842, TLx844	15	16	17	14.5	16	17.5	V
Start threshold voltage	TLx843, TLx845	7.8	8.4	9	7.8	8.4	9	V
Minimum operating valtage ofter startur	TLx842, TLx844	9	10	11	8.5	10	11.5	V
Minimum operating voltage after startup	TLx843, TLx845	7	7.6	8.2	7	7.6	8.2	V

[†] All typical values are at $T_A = 25$ °C.

NOTE 4: Adjust VCC above the start threshold before setting it to 15 V.

pulse-width-modulator section

PARAMETER			TL284x			TL384x		
			TYP†	MAX	MIN	TYP [†]	MAX	UNIT
Maximum duty cycle	TLx842, TLx843	95	97	100	95	97	100	
Maximum duty cycle	TLx844, TLx845	46	48	50	46	48	50	%
Minimum duty cycle		·		0			0	

[†] All typical values are at $T_A = 25^{\circ}C$.

NOTE 4: Adjust V_{CC} above the start threshold before setting it to 15 V.



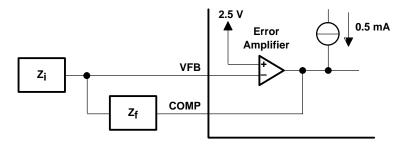
electrical characteristics over recommended operating free-air temperature range, V_{CC} = 15 V (see Note 4), R_T = 10 k Ω , C_T = 3.3 nF (unless otherwise specified) (continued)

supply voltage

PARAMETER	TEST CONDITIONS	TL284x			TL384x			UNIT
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP [†]	MAX	UNIT
Start-up current			0.5	1		0.5	1	mA
Operating supply current	VFB and ISENSE at 0 V		11	17		11	17	mA
Limiting voltage	I _{CC} = 25 mA		34			34		V

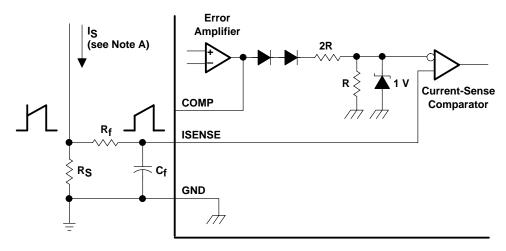
† All typical values are at $T_A = 25^{\circ}C$. NOTE 4: Adjust V_{CC} above the start threshold before setting it to 15 V.

APPLICATION INFORMATION



NOTE A: Error amplifier can source or sink up to 0.5 mA.

Figure 1. Error-Amplifier Configuration

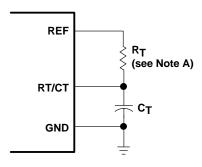


NOTE A: Peak current (Is) is determined by the formula:

$$I_{S(max)} = \frac{1 \text{ V}}{R_S}$$

$$\begin{split} I_{S(max)} &= \frac{1}{R_S} V \\ \text{A small RC filter formed by resistor } R_f \text{ and capacitor } C_f \text{ may be required to suppress switch transients.} \end{split}$$

Figure 2. Current-Sense Circuit

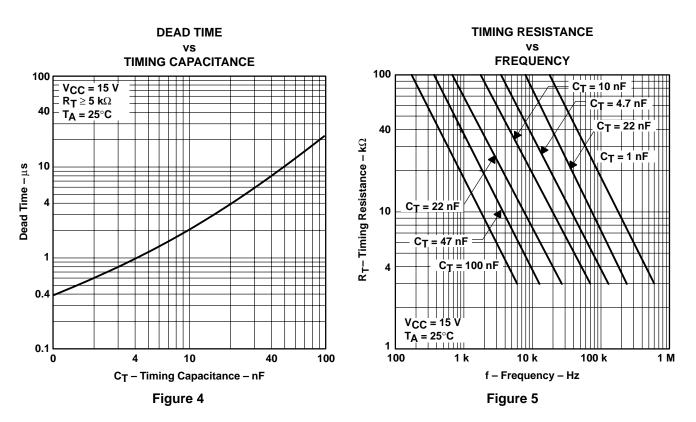


NOTE A: For RT > 5 k\Omega: $f \approx \frac{1.72}{R_T C_T}$

Figure 3. Oscillator Section



APPLICATION INFORMATION



open-loop laboratory test fixture

In the open-loop laboratory test fixture (see Figure 6), high peak currents associated with loads necessitate careful grounding techniques. Timing and bypass capacitors should be connected close to the GND terminal in a single-point ground. The transistor and 5-k Ω potentiometer sample the oscillator waveform and apply an adjustable ramp to the ISENSE terminal.

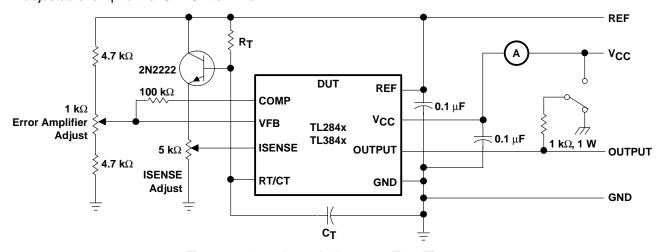


Figure 6. Open-Loop Laboratory Test Fixture



APPLICATION INFORMATION

shutdown technique

The PWM controller (see Figure 7) can be shut down by two methods: either raise the voltage at ISENSE above 1 V or pull the COMP terminal below a voltage two diode drops above ground. Either method causes the output of the PWM comparator to be high (refer to block diagram). The PWM latch is reset dominant so that the output remains low until the next clock cycle after the shutdown condition at the COMP or ISENSE terminal is removed. In one example, an externally latched shutdown can be accomplished by adding an SCR that resets by cycling V_{CC} below the lower UVLO threshold. At this point, the reference turns off, allowing the SCR to reset.

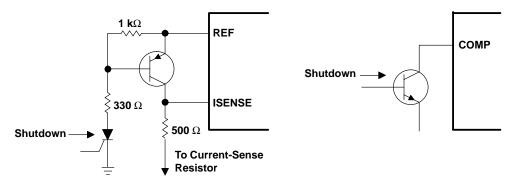


Figure 7. Shutdown Techniques

A fraction of the oscillator ramp can be summed resistively with the current-sense signal to provide slope compensation for converters requiring duty cycles over 50% (see Figure 8). Note that capacitor C forms a filter with R2 to suppress the leading-edge switch spikes.

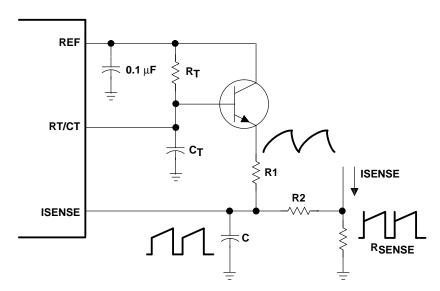


Figure 8. Slope Compensation









PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
TL2842D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL2842D-8	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL2842DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL2842DR-8	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL2842P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL2843D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL2843D-8	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL2843DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL2843DR-8	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL2843P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL2844D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL2844D-8	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL2844DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL2844DR-8	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL2844P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL2845D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL2845D-8	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL2845DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL2845DR-8	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL2845P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL3842D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL3842D-8	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL3842DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL3842DR-8	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL3842P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC





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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
TL3843D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL3843D-8	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL3843DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL3843DR-8	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL3843P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL3844D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL3844D-8	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL3844DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL3844DR-8	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL3844P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TL3845D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL3845D-8	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL3845DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL3845DR-8	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
TL3845P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

4-Mar-2005

incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

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D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AA.



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